

B. Patterning 분과

2020년 2월 13일(목), 10:45-12:00 / Room F (스페이드 I, 6층)

■ [TF2-B] Patterning Technology: Photolithography and Etch

좌장: 김현우 교수 (한양대학교)

TF2-B-1 10:45-11:00	Understanding the Exposure Process in the Extreme Ultra Violet Lithography Sang-Kong Kim <i>Department of Science, Hongik University</i>
TF2-B-2 11:00-11:30	[초청] EUV Patterning 시대에 대응하는 차세대 dry etching 기술의 준비 박종철 <i>삼성전자</i>
TF2-B-3 11:30-11:45	SiO₂ Etching Using Hydrofluoroethers: The Use of Low Global Warming Potential Materials for Plasma Etching Jun-Hyun Kim ¹ and Chang-Koo Kim ² ¹ <i>Institute of NT-IT Fusion Technology, Ajou University, </i> ² <i>Department of Chemical Engineering and Department of Energy Systems Research, Ajou University</i>
TF2-B-4 11:45-12:00	Influence of Pulse-modulated RF Source Plasma on Etch Characteristic of Nanoscale Patterned Copper Thin Film Using CH₃COOH/Ar Eun Taek Lim, Moon Hwan Cha, and Chee Won Chung <i>Department of Chemical Engineering, Inha University</i>